

METHOD AND APPARATUS FOR MANUFACTURING SEMICONDUCTOR DEVICE

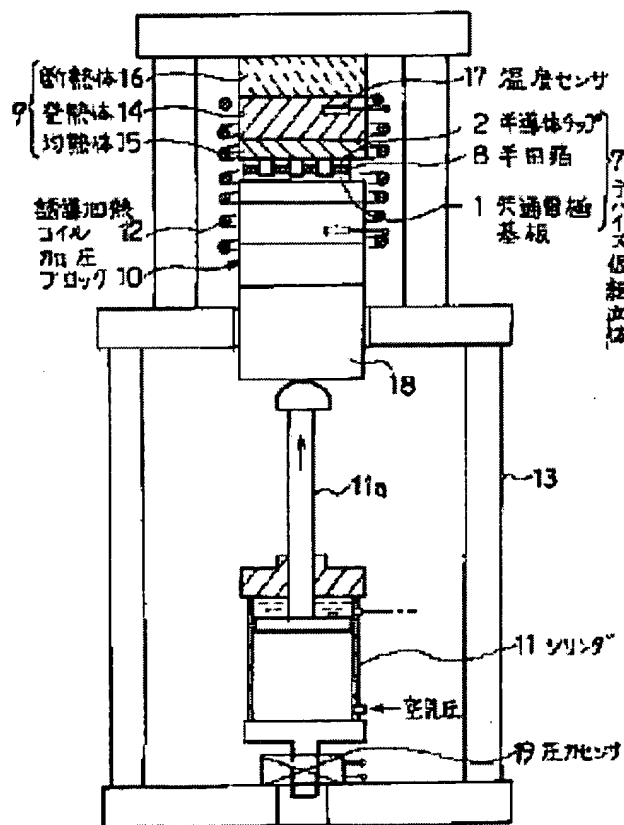
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Abstract of JP8055865

PURPOSE: To obtain a manufacturing apparatus by which a plurality of semiconductor chips juxtaposed and placed on a common electrode substrate can be mounted with good assembly accuracy so as to make their height uniform.

CONSTITUTION: A manufacturing apparatus is constituted in such a way that a fixed-side pressurization block 9 and a movable-side pressurization block 10 which are constituted of a heating element 14, a soaking body 15 and a heat insulator 16 and which sandwich a device temporary assembly 7, a cylinder 11, for pressurization, which is installed additionally at the movable-side pressurization block and an induction heating coil 12 which is arranged on the outer circumference of the heating element are combined with the device temporary assembly 7 in which a plurality of semiconductor chips 2 are juxtaposed and placed on a common electrode substrate 1 so as to be overlapped with a solder foil 8. Then, in a state that the device temporary assembly has been sandwiched between the pressurization blocks, a uniform pressurization force is applied to the respective semiconductor chips by operating the cylinder, and the semiconductor chips are heated by the induction heating coil so as to be mounted.



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